



Welcome to [E-XFL.COM](https://www.e-xfl.com)

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Discontinued at Digi-Key
Core Processor	RXv2
Core Size	32-Bit Single-Core
Speed	120MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, LINbus, MMC/SD, SCI, SPI, SSI, UART/USART, USB
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	127
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	64K x 8
RAM Size	552K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 29x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	176-LQFP
Supplier Device Package	176-LFQFP (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f564mfddfc-v1

Table 1.1 Outline of Specifications (9/9)

Classification	Module/Function	Description
Encryption function	AES*3	• Key lengths: 128, 192, and 256 bits • Support for CBC, ECB, CFB, OFB, CTR, and CMAC operating modes • Speed of calculations: 128-bit key length in 22 cycles 192-bit key length in 26 cycles 256-bit key length in 30 cycles • Compliant with FIPS PUB 197
	DES*3	• Key lengths: 56 bits (DES)/3 × 56 bits (T-DES) • Support for DES and triple DES • Support for ECB and CBC operating modes • Speed of calculations: 6 clock cycles in single DES mode 14 clock cycles in triple DES mode • Compliant with FIPS PUB 46-3 • Compliant with FIPS PUB 81
	SHA*3	• Support for SHA-1 (128), SHA-2 (224 or 256), and HMAC (160, 224, or 256) • Speed of calculations: 50 clock cycles in SHA-1 mode 42 clock cycles in SHA-224 mode 42 clock cycles in SHA-256 mode • Compliant with SHA as defined in FIPS PUB 180-1 and -2 • Compliant with HMAC as defined in FIPS PUB 198
	True random number generator (RNG)*3	• Length of random numbers: 16 bits • Generation of random-number-generated interrupts after a number is generated • Random number generation time: 3.6 ms (typ)
Operating frequency		Up to 120 MHz
Power supply voltage		VCC = AVCC0 = AVCC1 = VCC_USB = 2.7 to 3.6 V, $2.7 \leq VREFH0 \leq AVCC0$, VCC_USBA = AVCC_USBA = 2.7 to 3.6 V, VBATT = 2.0 to 3.6 V
Operating temperature		D-version: -40 to +85°C G-version: -40 to +105°C (in planning)
Package		177-pin TFLGA (PTLG0177KA-A) 176-pin LFBGA (PLBG0176GA-A) 176-pin LFQFP (PLQP0176KB-A) 145-pin TFLGA (PTLG0145KA-A) 144-pin LFQFP (PLQP0144KA-A) 100-pin TFLGA (PTLG0100JA-A) 100-pin LFQFP (PLQP0100KB-A)
On-chip debugging system		• E1 emulator (JTAG and FINE interfaces) • E20 emulator (JTAG interface)

Note 1. Magic Packet™ is a registered trademark of Advanced Micro Devices, Inc.

Note 2. Setting is only possible when the input sampling rate 44.1 kHz is selected.

Note 3. The product part number differs according to whether or not it supports encryption.

Note 4. The product part number differs according to whether or not it includes an SDHI (SD host interface).

1.4 Pin Functions

Table 1.4 lists the pin functions.

Table 1.4 Pin Functions (1/8)

Classifications	Pin Name	I/O	Description
Digital power supply	VCC	Input	Power supply pin. Connect this pin to the system power supply. Connect the pin to VSS via a 0.1-μF multilayer ceramic capacitor. The capacitor should be placed close to the pin.
	VCL	Input	Connect this pin to VSS via a 0.1-μF multilayer ceramic capacitor. The capacitor should be placed close to the pin.
	VSS	Input	Ground pin. Connect it to the system power supply (0 V).
	VBATT	Input	Backup power pin
Clock	XTAL	Output	Pins for a crystal resonator. An external clock signal can be input through the EXTAL pin.
	EXTAL	Input	
	BCLK	Output	Outputs the external bus clock for external devices.
	SDCLK	Output	Outputs the SDRAM-dedicated clock.
	XCOUT	Output	Input/output pins for the sub clock oscillator. Connect a crystal resonator between XCOUT and XCIN.
	XCIN	Input	
Clock frequency accuracy measurement	CACREF	Input	Reference clock input pin for the clock frequency accuracy measurement circuit
Operating mode control	MD	Input	Pins for setting the operating mode. The signal levels on these pins must not be changed during operation.
	UB	Input	USB boot mode or user boot mode enable pin
	UPSEL	Input	Selects the power supply method in USB boot mode. The low level selects self-power mode and the high level selects bus power mode.
System control	RES#	Input	Reset signal input pin. This LSI enters the reset state when this signal goes low.
	EMLE	Input	Input pin for the on-chip emulator enable signal. When the on-chip emulator is used, this pin should be driven high. When not used, it should be driven low.
	BSCANP	Input	Boundary scan enable pin. Boundary scan is enabled when this pin goes high. When not used, it should be driven low.
On-chip emulator	FINED	I/O	Fine interface pin
	TRST#	Input	On-chip emulator or boundary scan pins. When the EMLE pin is driven high, these pins are dedicated for the on-chip emulator.
	TMS	Input	
	TDI	Input	
	TCK	Input	
	TDO	Output	
	TRCLK	Output	This pin outputs the clock for synchronization with the trace data.
	TRSYNC	Output	This pin indicates that output from the TRDATA0 to TRDATA3 pins is valid.
	TRDATA0 to TRDATA3	Output	These pins output the trace information.
Address bus	A0 to A23	Output	Output pins for the address
Data bus	D0 to D31	I/O	Input and output pins for the bidirectional data bus
Multiplexed bus	A0/D0 to A15/D15	I/O	Address/data multiplexed bus

Table 1.7 List of Pin and Pin Functions (145-Pin TFLGA) (2/5)

Pin Number	Power Supply Clock System Control	I/O Port	Bus EXDMAC SDRAMC	Timer (MTU, GPT, TPU, TMR, PPG, RTC, CMTW, POE, CAC)	Communication (ETHERC, SCIG, SCIh, RSPI, RIIC, CAN, USB, SSI)	Memory Interface Camera Interface (QSPI, SDHI, MMCIF, PDC)	Interrupt	S12ADC, R12DA
C9		PD7	D7[A7/D7]	MTIC5U/POE0#		MMC_D1-B/ SDHI_D1-B/ QIO1-B/QMI-B	IRQ7	AN107
C10		P63	CS3#/CAS#					
C11		PE0	D8[A8/D8]	MTIOC3D/ GTIOC2B-A	SCK12	MMC_D4-B		ANEX0
C12		P70	SDCLK					
C13	VSS							
D1		P00		TMRI0	TXD6/SMOSI6/SSDA6		IRQ8	AN118
D2		PF5					IRQ4	
D3		P03					IRQ11	DA0
D4		P01		TMCIO	RXD6/SMISO6/SSCL6		IRQ9	AN119
D5	VCC							
D6		P93	A19	POE0#	CTS7#/RTS7#/SS7#			AN117
D7		PD5	D5[A5/D5]	MTIC5W/MTIOC8C/ POE10#		MMC_CLK-B/ SDHI_CLK-B/ QSPCLK-B	IRQ5	AN113
D8		P60	CS0#					
D9		P64	CS4#/WE#					
D10		PE7	D15[A15/D15]	MTIOC6A/ GTIOC3A-E/TOC1		MMC_RES#-B/ SDHI_WP-B	IRQ7	AN105
D11	VCC							
D12		PE5	D13[A13/D13]	MTIOC4C/MTIOC2B/ GTIOC0A-A	ET0_RX_CLK/ REF50CK0		IRQ5	AN103
D13		PE6	D14[A14/D14]	MTIOC6C/GTIOC3B- E/TIC1		MMC_CD-B/ SDHI_CD-B	IRQ6	AN104
E1	VSS							
E2	VCL							
E3		PJ5		POE8#	CTS2#/RTS2#/SS2#			
E4	EMLE							
E5		P44					IRQ12- DS	AN004
E10		PA0	A0/BC0#	MTIOC4A/MTIOC6D/ GTIOC0B-C/TIOCA0/ CACREF/PO16	SSLA1-B/ ET0_TX_EN/ RMII0_TXD_EN			
E11		P66	CS6#/DQM0	MTIOC7D/ GTIOC2B-C	CTX2			
E12		P65	CS5#/CKE					
E13		P67	CS7#/DQM1	MTIOC7C/ GTIOC1B-C	CRX2		IRQ15	
F1	XCIN							
F2	XCOU							
F3		PJ3	EDACK1	MTIOC3C	ET0_EXOUT/CTS6#/ RTS6#/CTS0#/RTS0#/ SS6#/SS0#			
F4	VBATT							
F10		PA3	A3	MTIOC0D/MTCLKD/ TIOC0D/TCLKB/PO19	RXD5/SMISO5/ SSCL5/ET0_MDIO		IRQ6-DS	
F11	VSS							
F12		PA1	A1	MTIOC0B/MTCLKC/ MTIOC7B/ GTIOC2A-C/TIOC0B/ PO17	SCK5/SSLA2-B/ ET0_WOL		IRQ11	

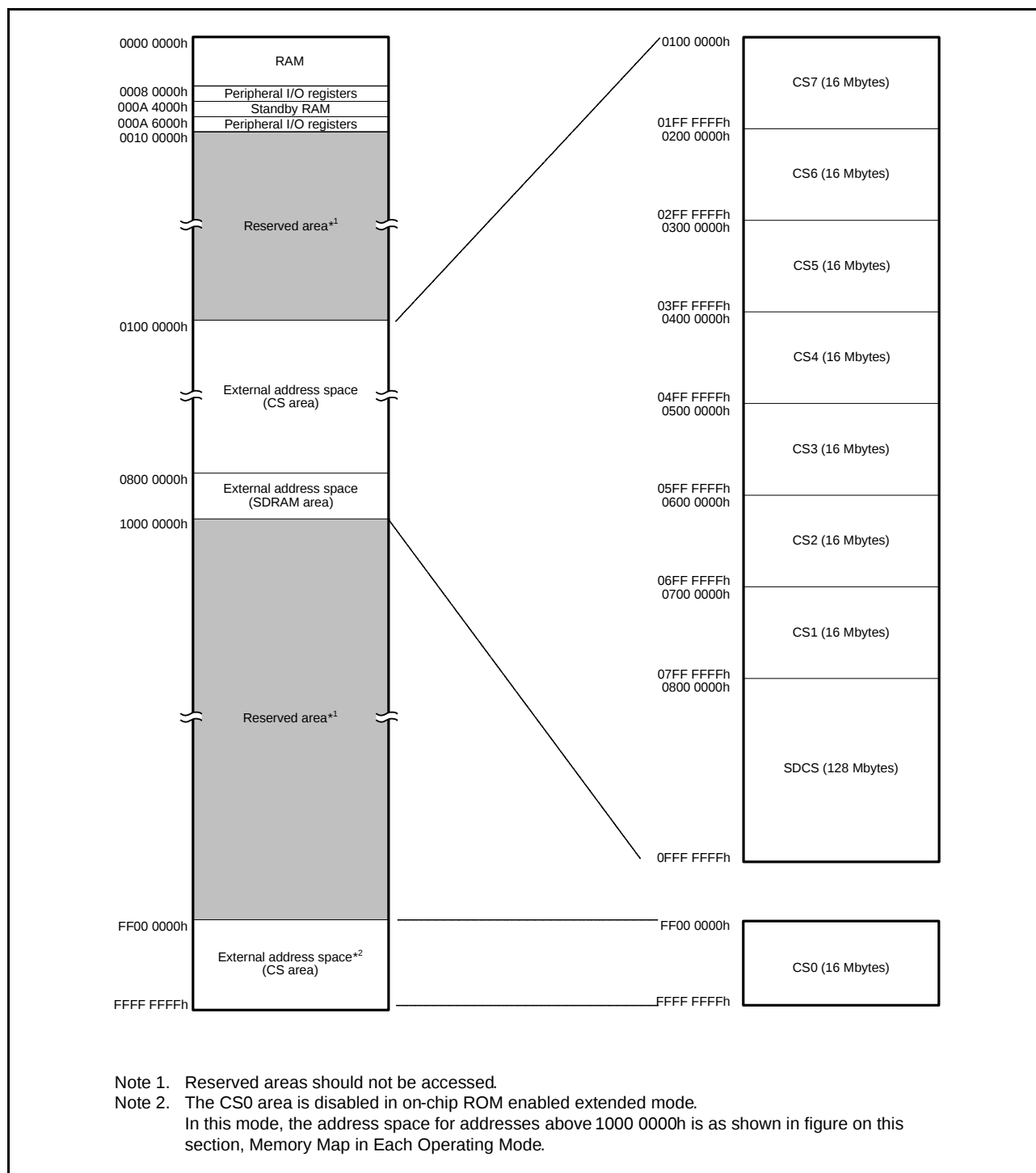
Table 1.10 List of Pin and Pin Functions (100-Pin LFQFP) (3/4)

Pin Number	Power Supply Clock System Control	I/O Port	Bus EXDMAC	Timer (MTU, GPT, TPU, TMR, PPG, RTC, CMTW, POE, CAC)	Communication (ETHERC, SCIG, SCIh, RSPI, RIIC, CAN, USB, SSI)	Memory Interface Camera Interface (QSPI, SDHI, MMCIF, PDC)	Interrupt	S12ADC, R12DA
57		PB3	A11	MTIOC0A/MTIOC4A/ TIOC0D3/TCLKD/ TMO0/PO27/POE11#	SCK6/ET0_RX_ER/ RMII0_RX_ER			
58		PB2	A10	TIOCC3/TCLKC/ PO26	CTS6#/RTS6#SS6#/ ET0_RX_CLK/ REF50CK0			
59		PB1	A9	MTIOC0C/MTIOC4C/ TIOCB3/TMCI0/PO25	TXD6/SMOSI6/ SSDA6/ET0_ERXD0/ RMII0_RXD0		IRQ4-DS	
60	VCC							
61		PB0	A8	MTIC5W/TIOCA3/ PO24	RXD6/SMISO6/ SSCL6/ET0_ERXD1/ RMII0_RXD1		IRQ12	
62	VSS							
63		PA7	A7	TIOCB2/PO23	MISOA-B/ET0_WOL			
64		PA6	A6	MTIC5V/MTCLKB/ GTETRG-C/TIOCA2/ TMCI3/PO22/POE10#	CTS5#/RTS5#SS5#/ MOSIA-B/ ET0_EXOUT			
65		PA5	A5	MTIOC6B/TIOCB1/ GTIOC0A-C/PO21	RSPCKA-B/ ET0_LINKSTA			
66		PA4	A4	MTIC5U/MTCLKA/ TIOCA1/TMRI0/PO20	TXD5/SMOSI5/ SSDA5/SSLA0-B/ ET0_MDC		IRQ5-DS	
67		PA3	A3	MTIOC0D/MTCLKD/ TIOC0D3/TCLKB/PO19	RXD5/SMISO5/ SSCL5/ET0_MDIO		IRQ6-DS	
68		PA2	A2	MTIOC7A/ GTIOC1A-C/PO18	RXD5/SMISO5/ SSCL5/SSLA3-B			
69		PA1	A1	MTIOC0B/MTCLKC/ MTIOC7B/ GTIOC2A-C/TIOCB0/ PO17	SCK5/SSLA2-B/ ET0_WOL		IRQ11	
70		PA0	A0/BC0#	MTIOC4A/MTIOC6D/ GTIOC0B-C/TIOCA0/ CACREF/PO16	SSLA1-B/ ET0_TX_EN/ RMII0_TXD_EN			
71		PE7	D15[A15/D15]	MTIOC6A/ GTIOC3A-E/TOC1		MMC_RES#-B/ SDHI_WP-B	IRQ7	AN105
72		PE6	D14[A14/D14]	MTIOC6C/GTIOC3B- E/TIC1		MMC_CD-B/ SDHI_CD-B	IRQ6	AN104
73		PE5	D13[A13/D13]	MTIOC4C/MTIOC2B/ GTIOC0A-A	ET0_RX_CLK/ REF50CK0		IRQ5	AN103
74		PE4	D12[A12/D12]	MTIOC4D/MTIOC1A/ GTIOC1A-A/PO28	ET0_ERXD2			AN102
75		PE3	D11[A11/D11]	MTIOC4B/ GTIOC2A-A/PO26/ POE8#/TOC3	CTS12#/RTS12#/ SS12#/ET0_ERXD3	MMC_D7-B		AN101
76		PE2	D10[A10/D10]	MTIOC4A/ GTIOC0B-A/PO23/ TIC3	RXD12/SMISO12/ SSCL12/RXD12	MMC_D6-B	IRQ7-DS	AN100
77		PE1	D9[A9/D9]	MTIOC4C/MTIOC3B/ GTIOC1B-A/PO18	TXD12/SMOSI12/ SSDA12/TXD12/ SIOX12	MMC_D5-B		ANEX1
78		PE0	D8[A8/D8]	MTIOC3D/ GTIOC2B-A	SCK12	MMC_D4-B		ANEX0
79		PD7	D7[A7/D7]	MTIC5U/POE0#		MMC_D1-B/ SDHI_D1-B/ QIO1-B/ QMI-B	IRQ7	AN107
80		PD6	D6[A6/D6]	MTIC5V/MTIOC8A/ POE4#		MMC_D0-B/ SDHI_D0-B/ QIO0-B/ QMO-B	IRQ6	AN106

3.2 External Address Space

The external address space is divided into CS areas (CS0 to CS7) and SDRAM area (SDCS). The CS areas are divided into up to eight areas (CS0 to CS7), each corresponding to the CSn# signal output from a CSn# (n = 0 to 7) pin.

Figure 3.2 shows the address ranges corresponding to the individual CS areas (CS0 to CS7) and SDRAM areas (SDCS) in on-chip ROM disabled extended mode.



**Figure 3.2 Correspondence between External Address Spaces and CS Areas
(In On-Chip ROM Disabled Extended Mode)**

4.1 I/O Register Addresses (Address Order)

Table 4.1 List of I/O Registers (Address Order) (1 / 67)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles		Related Function
						ICLK $\geq$ PCLK	ICLK $<$ PCLK	
0008 0000h	SYSTM	Mode Monitor Register	MDMONR	16	16	3 ICLK		Operating Modes
0008 0002h	SYSTM	Mode Status Register	MDSR	16	16	3 ICLK		Operating Modes
0008 0006h	SYSTM	System Control Register 0	SYSCR0	16	16	3 ICLK		Operating Modes
0008 0008h	SYSTM	System Control Register 1	SYSCR1	16	16	3 ICLK		Operating Modes
0008 000Ch	SYSTM	Standby Control Register	SBYCR	16	16	3 ICLK		Low Power Consumption
0008 0010h	SYSTM	Module Stop Control Register A	MSTPCRA	32	32	3 ICLK		Low Power Consumption
0008 0014h	SYSTM	Module Stop Control Register B	MSTPCRB	32	32	3 ICLK		Low Power Consumption
0008 0018h	SYSTM	Module Stop Control Register C	MSTPCRC	32	32	3 ICLK		Low Power Consumption
0008 001Ch	SYSTM	Module Stop Control Register D	MSTPCRD	32	32	3 ICLK		Low Power Consumption
0008 0020h	SYSTM	System Clock Control Register	SCKCR	32	32	3 ICLK		Clock Generation Circuit
0008 0024h	SYSTM	System Clock Control Register 2	SCKCR2	16	16	3 ICLK		Clock Generation Circuit
0008 0026h	SYSTM	System Clock Control Register 3	SCKCR3	16	16	3 ICLK		Clock Generation Circuit
0008 0028h	SYSTM	PLL Control Register	PLLCR	16	16	3 ICLK		Clock Generation Circuit
0008 002Ah	SYSTM	PLL Control Register 2	PLLCR2	8	8	3 ICLK		Clock Generation Circuit
0008 0030h	SYSTM	External Bus Clock Control Register	BCKCR	8	8	3 ICLK		Clock Generation Circuit
0008 0032h	SYSTM	Main Clock Oscillator Control Register	MOSCCR	8	8	3 ICLK		Clock Generation Circuit
0008 0033h	SYSTM	Sub-Clock Oscillator Control Register	SOSCCR	8	8	3 ICLK		Clock Generation Circuit
0008 0034h	SYSTM	Low-Speed On-Chip Oscillator Control Register	LOCOCR	8	8	3 ICLK		Clock Generation Circuit

Table 4.1 List of I/O Registers (Address Order) (2 / 67)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles		Related Function
						ICLK $\geq$ PCLK	ICLK < PCLK	
0008 0035h	SYSTEM	IWDT-Dedicated On-Chip Oscillator Control Register	ILOCOCR	8	8	3 ICLK		Clock Generation Circuit
0008 0036h	SYSTEM	High-Speed On-Chip Oscillator Control Register	HOCOCR	8	8	3 ICLK		Clock Generation Circuit
0008 0037h	SYSTEM	High-Speed On-Chip Oscillator Control Register 2	HOCOCR2	8	8	3 ICLK		Clock Generation Circuit
0008 003Ch	SYSTEM	Oscillation Stabilization Flag Register	OSCOVFSR	8	8	3 ICLK		Clock Generation Circuit
0008 0040h	SYSTEM	Oscillation Stop Detection Control Register	OSTDCR	8	8	3 ICLK		Clock Generation Circuit
0008 0041h	SYSTEM	Oscillation Stop Detection Status Register	OSTDSR	8	8	3 ICLK		Clock Generation Circuit
0008 00A0h	SYSTEM	Operating Power Control Register	OPCCR	8	8	3 ICLK		Low Power Consumption
0008 00A1h	SYSTEM	Sleep Mode Return Clock Source Switching Register	RSTCKCR	8	8	3 ICLK		Low Power Consumption
0008 00A2h	SYSTEM	Main Clock Oscillator Wait Control Register	MOSCWTCR	8	8	3 ICLK		Clock Generation Circuit
0008 00A3h	SYSTEM	Sub-Clock Oscillator Wait Control Register	SOSCWTCR	8	8	3 ICLK		Clock Generation Circuit
0008 00C0h	SYSTEM	Reset Status Register 2	RSTSR2	8	8	3 ICLK		Resets
0008 00C2h	SYSTEM	Software Reset Register	SWRR	16	16	3 ICLK		Resets
0008 00E0h	SYSTEM	Voltage Monitoring 1 Circuit Control Register 1	LVD1CR1	8	8	3 ICLK		LVDA
0008 00E1h	SYSTEM	Voltage Monitoring 1 Circuit Status Register	LVD1SR	8	8	3 ICLK		LVDA
0008 00E2h	SYSTEM	Voltage Monitoring 2 Circuit Control Register 1	LVD2CR1	8	8	3 ICLK		LVDA
0008 00E3h	SYSTEM	Voltage Monitoring 2 Circuit Status Register	LVD2SR	8	8	3 ICLK		LVDA
0008 03FEh	SYSTEM	Protect Register	PRCR	16	16	3 ICLK		Register Write Protection Function
0008 1200h	RAM	RAM Operating Mode Control Register	RAMMODE	8	8	2 ICLK		RAM
0008 1201h	RAM	RAM Error Status Register	RAMSTS	8	8	2 ICLK		RAM
0008 1204h	RAM	RAM Protection Register	RAMPRCR	8	8	2 ICLK		RAM
0008 1208h	RAM	RAM Error Address Capture Register	RAMECAD	32	32	2 ICLK		RAM
0008 12C0h	ECCRAM	ECCRAM Operating Mode Control Register	ECCRAMMODE	8	8	2 ICLK		RAM
0008 12C1h	ECCRAM	ECCRAM 2-Bit Error Status Register	ECCRAM2STS	8	8	2 ICLK		RAM
0008 12C2h	ECCRAM	ECCRAM 1-Bit Error Information Update Enable Register	ECCRAM1STSEN	8	8	2 ICLK		RAM

Table 4.1 List of I/O Registers (Address Order) (5 / 67)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles		Related Function
						ICLK $\geq$ PCLK	ICLK < PCLK	
0008 21DCh	DMAC7	DMA Transfer Enable Register	DMCNT	8	8	2 ICLK		DMACaA
0008 21DDh	DMAC7	DMA Software Start Register	DMREQ	8	8	2 ICLK		DMACaA
0008 21DEh	DMAC7	DMA Status Register	DMSTS	8	8	2 ICLK		DMACaA
0008 21DFh	DMAC7	DMA Request Source Flag Control Register	DMCSL	8	8	2 ICLK		DMACaA
0008 2200h	DMAC	DMAC Module Start Register	DMAST	8	8	2 ICLK		DMACaA
0008 2204h	DMAC	DMAC74 Interrupt Status Monitor Register	DMIST	8	8	2 ICLK		DMACaA
0008 2400h	DTC	DTC Control Register	DTCCR	8	8	2 ICLK		DTCa
0008 2404h	DTC	DTC Vector Base Register	DTCVBR	32	32	2 ICLK		DTCa
0008 2408h	DTC	DTC Address Mode Register	DTCADMOD	8	8	2 ICLK		DTCa
0008 240Ch	DTC	DTC Module Start Register	DTCST	8	8	2 ICLK		DTCa
0008 240Eh	DTC	DTC Status Register	DTCSTS	16	16	2 ICLK		DTCa
0008 2800h	EXDMA C0	EXDMA Source Address Register	EDMSAR	32	32	1, 2 BCLK		EXDMA Ca
0008 2804h	EXDMA C0	EXDMA Destination Address Register	EDMDAR	32	32	1, 2 BCLK		EXDMA Ca
0008 2808h	EXDMA C0	EXDMA Transfer Count Register	EDMCRA	32	32	1, 2 BCLK		EXDMA Ca
0008 280Ch	EXDMA C0	EXDMA Block Transfer Count Register	EDMCRB	16	16	1, 2 BCLK		EXDMA Ca
0008 2810h	EXDMA C0	EXDMA Transfer Mode Register	EDMTMD	16	16	1, 2 BCLK		EXDMA Ca
0008 2812h	EXDMA C0	EXDMA Output Setting Register	EDMOMD	8	8	1, 2 BCLK		EXDMA Ca
0008 2813h	EXDMA C0	EXDMA Interrupt Setting Register	EDMINT	8	8	1, 2 BCLK		EXDMA Ca
0008 2814h	EXDMA C0	EXDMA Address Mode Register	EDMAMD	32	32	1, 2 BCLK		EXDMA Ca
0008 2818h	EXDMA C0	EXDMA Offset Register	EDMOFR	32	32	1, 2 BCLK		EXDMA Ca
0008 281Ch	EXDMA C0	EXDMA Transfer Enable Register	EDMCNT	8	8	1, 2 BCLK		EXDMA Ca
0008 281Dh	EXDMA C0	EXDMA Software Start Register	EDMREQ	8	8	1, 2 BCLK		EXDMA Ca
0008 281Eh	EXDMA C0	EXDMA Status Register	EDMSTS	8	8	1, 2 BCLK		EXDMA Ca
0008 2820h	EXDMA C0	EXDMA External Request Sense Mode Register	EDMRMD	8	8	1, 2 BCLK		EXDMA Ca
0008 2821h	EXDMA C0	EXDMA External Request Flag Register	EDMERF	8	8	1, 2 BCLK		EXDMA Ca
0008 2822h	EXDMA C0	EXDMA Peripheral Request Flag Register	EDMPRF	8	8	1, 2 BCLK		EXDMA Ca
0008 2840h	EXDMA C1	EXDMA Source Address Register	EDMSAR	32	32	1, 2 BCLK		EXDMA Ca
0008 2844h	EXDMA C1	EXDMA Destination Address Register	EDMDAR	32	32	1, 2 BCLK		EXDMA Ca
0008 2848h	EXDMA C1	EXDMA Transfer Count Register	EDMCRA	32	32	1, 2 BCLK		EXDMA Ca
0008 284Ch	EXDMA C1	EXDMA Block Transfer Count Register	EDMCRB	16	16	1, 2 BCLK		EXDMA Ca
0008 2850h	EXDMA C1	EXDMA Transfer Mode Register	EDMTMD	16	16	1, 2 BCLK		EXDMA Ca
0008 2852h	EXDMA C1	EXDMA Output Setting Register	EDMOMD	8	8	1, 2 BCLK		EXDMA Ca
0008 2853h	EXDMA C1	EXDMA Interrupt Setting Register	EDMINT	8	8	1, 2 BCLK		EXDMA Ca
0008 2854h	EXDMA C1	EXDMA Address Mode Register	EDMAMD	32	32	1, 2 BCLK		EXDMA Ca
0008 285Ch	EXDMA C1	EXDMA Transfer Enable Register	EDMCNT	8	8	1, 2 BCLK		EXDMA Ca

Table 4.1 List of I/O Registers (Address Order) (28 / 67)

Address	Module Symbol	Register Name	Register Symbol	Number of Bits	Access Size	Number of Access Cycles		Related Function
						ICLK ≥ PCLK	ICLK < PCLK	
0008 B004h	CAC	CAC Status Register	CASTR	8	8	2, 3 PCLKB	2 ICLK	CAC
0008 B006h	CAC	CAC Upper-Limit Value Setting Register	CAULVR	16	16	2, 3 PCLKB	2 ICLK	CAC
0008 B008h	CAC	CAC Lower-Limit Value Setting Register	CALLVR	16	16	2, 3 PCLKB	2 ICLK	CAC
0008 B00Ah	CAC	CAC Counter Buffer Register	CACNTBR	16	16	2, 3 PCLKB	2 ICLK	CAC
0008 B080h	DOC	DOC Control Register	DOCR	8	8	2, 3 PCLKB	2 ICLK	DOC
0008 B082h	DOC	DOC Data Input Register	DODIR	16	16	2, 3 PCLKB	2 ICLK	DOC
0008 B084h	DOC	DOC Data Setting Register	DODSR	16	16	2, 3 PCLKB	2 ICLK	DOC
0008 B100h	ELC	Event Link Control Register	ELCR	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B101h	ELC	Event Link Setting Register 0	ELSR0	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B104h	ELC	Event Link Setting Register 3	ELSR3	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B105h	ELC	Event Link Setting Register 4	ELSR4	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B108h	ELC	Event Link Setting Register 7	ELSR7	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B10Bh	ELC	Event Link Setting Register 10	ELSR10	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B10Ch	ELC	Event Link Setting Register 11	ELSR11	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B10Dh	ELC	Event Link Setting Register 12	ELSR12	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B10Eh	ELC	Event Link Setting Register 13	ELSR13	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B110h	ELC	Event Link Setting Register 15	ELSR15	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B111h	ELC	Event Link Setting Register 16	ELSR16	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B113h	ELC	Event Link Setting Register 18	ELSR18	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B114h	ELC	Event Link Setting Register 19	ELSR19	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B115h	ELC	Event Link Setting Register 20	ELSR20	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B116h	ELC	Event Link Setting Register 21	ELSR21	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B117h	ELC	Event Link Setting Register 22	ELSR22	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B118h	ELC	Event Link Setting Register 23	ELSR23	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B119h	ELC	Event Link Setting Register 24	ELSR24	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B11Ah	ELC	Event Link Setting Register 25	ELSR25	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B11Bh	ELC	Event Link Setting Register 26	ELSR26	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B11Ch	ELC	Event Link Setting Register 27	ELSR27	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B11Dh	ELC	Event Link Setting Register 28	ELSR28	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B11Fh	ELC	Event Link Option Setting Register A	ELOPA	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B120h	ELC	Event Link Option Setting Register B	ELOPB	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B121h	ELC	Event Link Option Setting Register C	ELOPC	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B122h	ELC	Event Link Option Setting Register D	ELOPD	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B123h	ELC	Port Group Setting Register 1	PGR1	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B124h	ELC	Port Group Setting Register 2	PGR2	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B125h	ELC	Port Group Control Register 1	PGC1	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B126h	ELC	Port Group Control Register 2	PGC2	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B127h	ELC	Port Buffer Register 1	PDBF1	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B128h	ELC	Port Buffer Register 2	PDBF2	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B129h	ELC	Event Link Port Setting Register 0	PEL0	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B12Ah	ELC	Event Link Port Setting Register 1	PEL1	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B12Bh	ELC	Event Link Port Setting Register 2	PEL2	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B12Ch	ELC	Event Link Port Setting Register 3	PEL3	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B12Dh	ELC	Event Link Software Event Generation Register	ELSEGR	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B131h	ELC	Event Link Setting Register 33	ELSR33	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B133h	ELC	Event Link Setting Register 35	ELSR35	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B134h	ELC	Event Link Setting Register 36	ELSR36	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B135h	ELC	Event Link Setting Register 37	ELSR37	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B136h	ELC	Event Link Setting Register 38	ELSR38	8	8	2, 3 PCLKB	2 ICLK	ELC
0008 B139h	ELC	Event Link Setting Register 41	ELSR41	8	8	2, 3 PCLKB	2 ICLK	ELC

5.2 DC Characteristics

Table 5.2 DC Characteristics (1)

Conditions: $V_{CC} = AV_{CC0} = AV_{CC1} = V_{CC_USB} = V_{BATT} = 2.7$ to 3.6 V, $2.7 \leq V_{REFH0} \leq AV_{CC0}$,
 $V_{CC_USBA} = AV_{CC_USBA} = 3.0$ to 3.6 V,
 $V_{SS} = AV_{SS0} = AV_{SS1} = V_{REFL0} = V_{SS_USB} = V_{SS1_USBA} = V_{SS2_USBA} = PV_{SS_USBA} = AV_{SS_USBA} = 0$ V,
 $T_a = T_{opr}$

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions					
Schmitt trigger input voltage	IRQ input pin*1	V_{IH}	$VCC \times 0.8$	—	$VCC + 0.3$	V						
	MTU input pin*1	V_{IL}	−0.3	—	$VCC \times 0.2$							
	GPT input pin*1	ΔV_T	$VCC \times 0.06$	—	—							
	POE3 input pin*1											
	TPU input pin*1											
	TMR input pin*1											
	SCI input pin*1											
	ADTRG# input pin*1	RIIC input pin (except for SMBus)	V_{IH}	$VCC \times 0.7$	—			$VCC + 3.6$ (≤ 5.8 max.)				
	RES#, NMI								V_{IL}	−0.3	—	$VCC \times 0.3$
		ΔV_T	$VCC \times 0.05$	—	—							
Ports for 5 V tolerant*2	V_{IH}	$VCC \times 0.8$	—	$VCC + 3.6$ (≤ 5.8 max.)								
					V_{IL}	−0.3	—	$VCC \times 0.2$				
Other input pins excluding ports for 5 V tolerant*3	V_{IH}	$VCC \times 0.8$	—	$VCC + 0.3$								
					V_{IL}	−0.3	—	$VCC \times 0.2$				
Input high voltage (except for Schmitt trigger input pin)	MD pin, EMLE	V_{IH}	$VCC \times 0.9$	—	$VCC + 0.3$	V						
	EXTAL, RSPI input pin, EXDMAC input pin, WAIT#, TCK, SSI input pin, SDHI input pin, MMC input pin, PDC input pin, QSPI input pin		$VCC \times 0.8$	—	$VCC + 0.3$							
	ETHERC input pin		2.3	—	$VCC + 0.3$							
	D0 to D31		$VCC \times 0.7$	—	$VCC + 0.3$							
	RIIC (SMBus)		2.1	—	5.8							
Input low voltage (except for Schmitt trigger input pin)	MD pin, EMLE	V_{IL}	−0.3	—	$VCC \times 0.1$	V						
	EXTAL, RSPI input pin, ETHERC input pin, EXDMAC input pin, WAIT#, TCK, SSI input pin, SDHI input pin, MMC input pin, PDC input pin, QSPI input pin		−0.3	—	$VCC \times 0.2$							
	D0 to D31		−0.3	—	$VCC \times 0.3$							
	RIIC (SMBus)		−0.3	—	0.8							

Note 1. This does not include the pins, which are multiplexed as ports for 5 V tolerant.

Note 2. Ports 07, 11 to 17, 20, 21, 30 to 33, 67, and C0 to C3 are 5 V tolerant.

Note 3. For P32, P31, and P30, input as follows when the V_{BATT} power supply is selected.

V_{IH} Min. = $V_{BATT} \times 0.8$, V_{IH} Max. = $V_{BATT} + 0.3$, V_{IL} Min. = -0.3 , V_{IL} Max. = $V_{BATT} \times 0.2$ ($V_{BATT} = 2.0$ to 3.6 V)

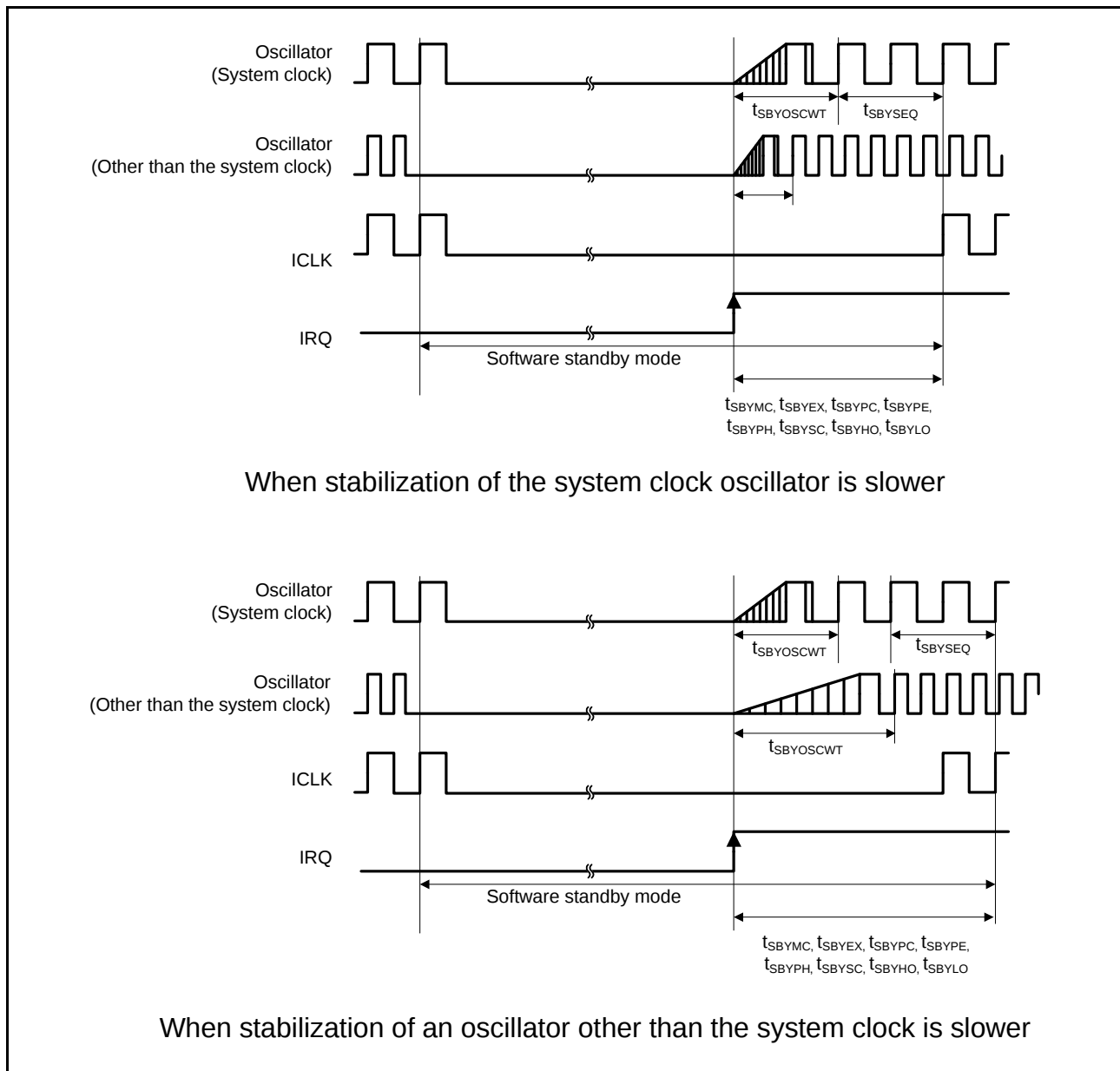


Figure 5.12 Software Standby Mode Cancellation Timing

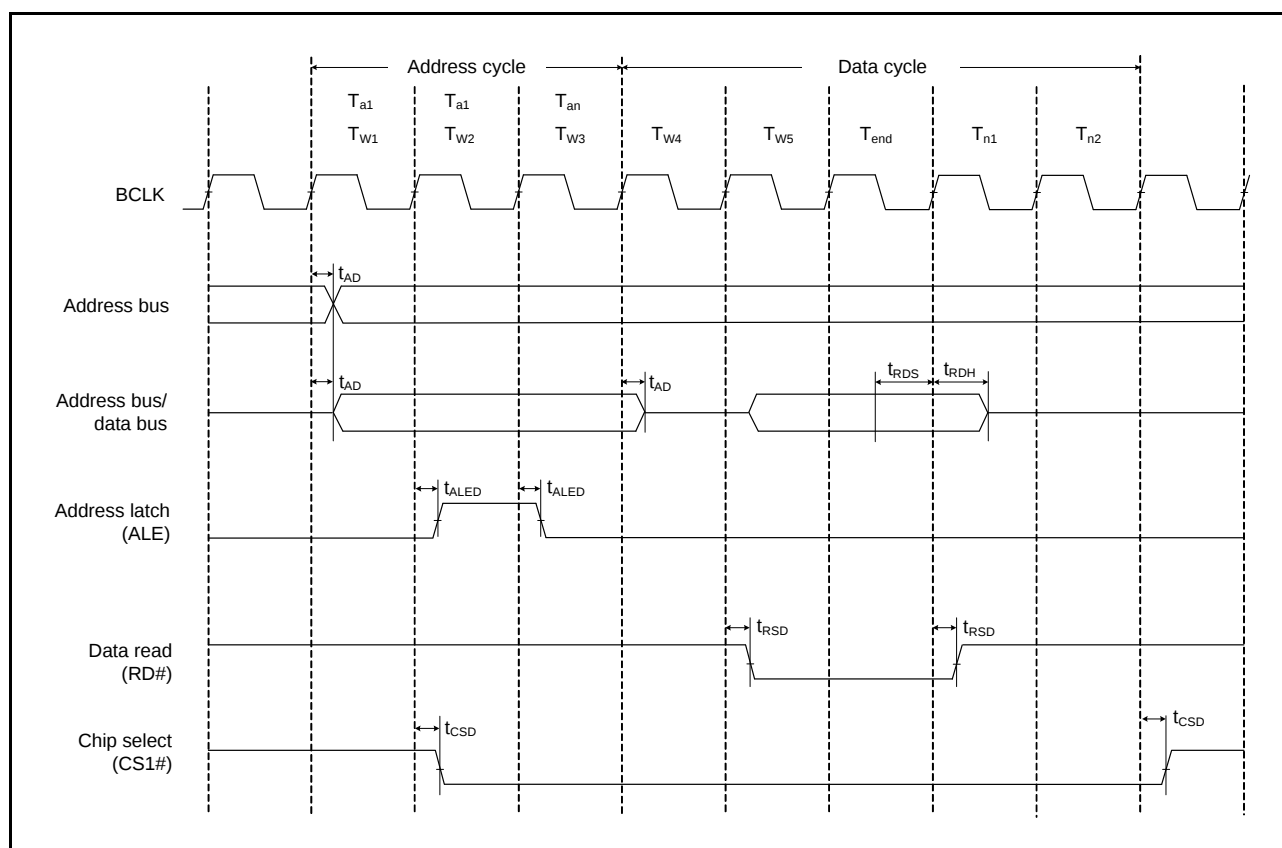


Figure 5.16 Address/Data Multiplexed Bus Read Access Timing

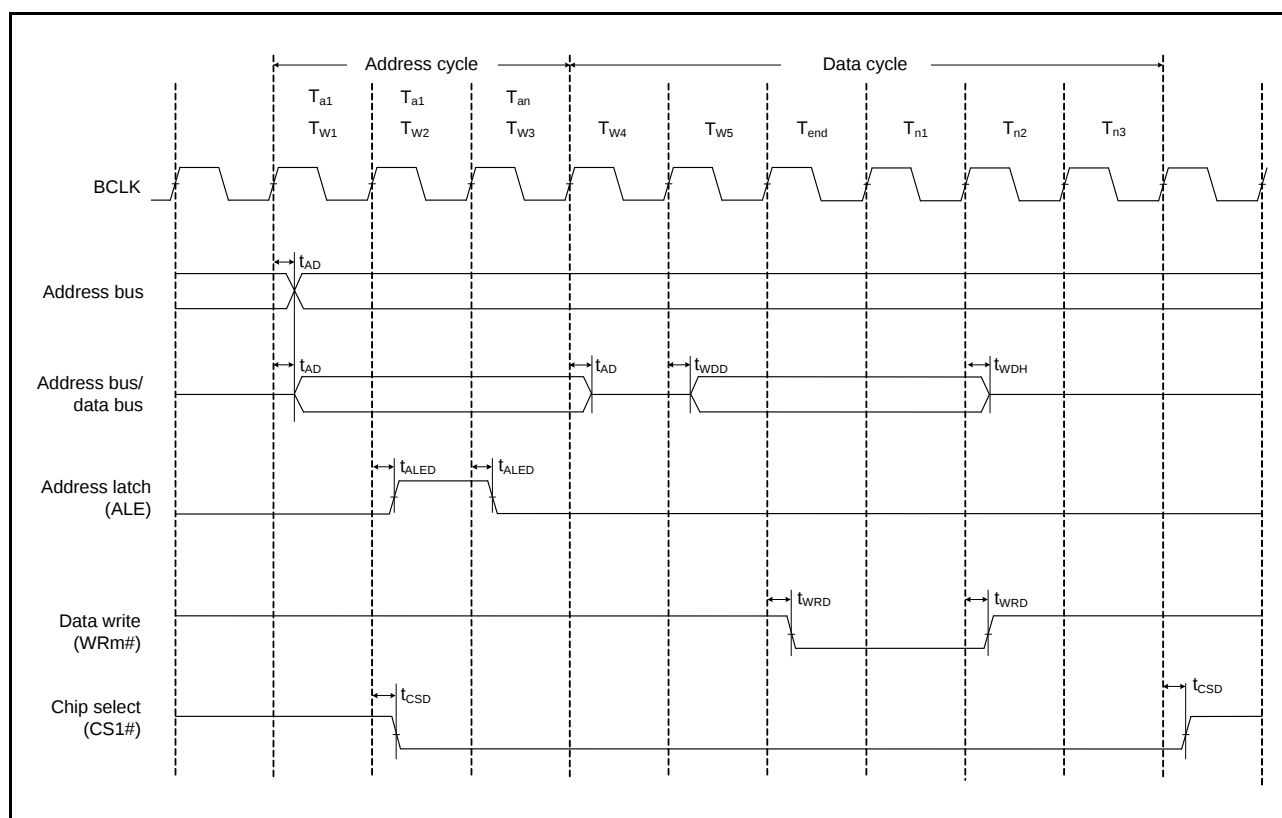


Figure 5.17 Address/Data Multiplexed Bus Write Access Timing

Table 5.28 POE3 Timing

Conditions: $V_{CC} = AVCC0 = AVCC1 = V_{CC_USB} = V_{BATT} = 2.7$ to 3.6 V, $2.7 \leq V_{REFH0} \leq AVCC0$,
 $V_{CC_USBA} = AVCC_USBA = 3.0$ to 3.6 V,
 $V_{SS} = AVSS0 = AVSS1 = V_{REFL0} = V_{SS_USB} = V_{SS1_USBA} = V_{SS2_USBA} = PV_{SS_USBA} = AV_{SS_USBA} = 0$ V,
 $PCLKA = 8$ to 120 MHz, $PCLKB = 8$ to 60 MHz, $T_a = T_{opr}$
Output load conditions: $V_{OH} = V_{CC} \times 0.5$, $V_{OL} = V_{CC} \times 0.5$, $C = 30$ pF
High-drive output is selected by the driving ability control register.

Item		Symbol	Min.	Max.	Unit*1	Test Conditions
POE	POE# input pulse width	t_{POEW}	1.5	—	t_{PBcyc}	Figure 5.40

Note 1. t_{PBcyc} : PCLKB cycle

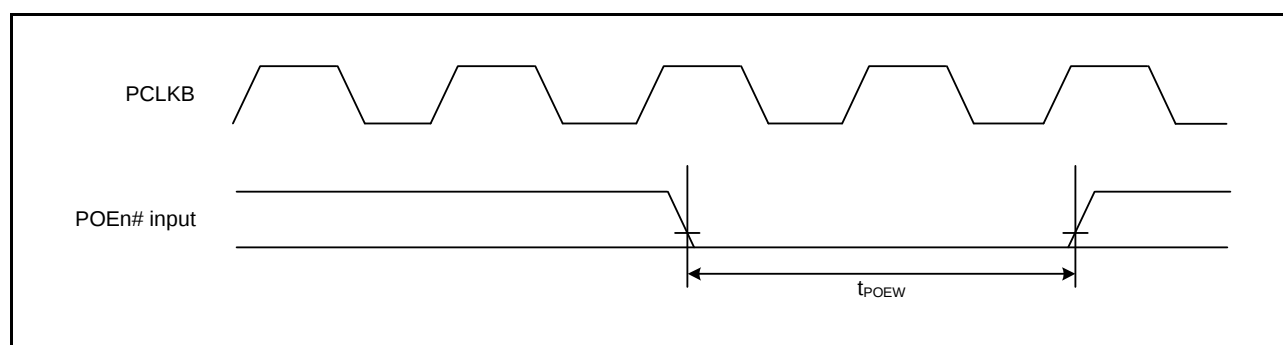
**Figure 5.40 POE# Input Timing**

Table 5.33 RSPI Timing

Conditions: $V_{CC} = AVCC0 = AVCC1 = V_{CC_USB} = V_{BATT} = 2.7$ to 3.6 V, $2.7 \leq V_{REFH0} \leq AVCC0$,
 $V_{CC_USBA} = AVCC_USBA = 3.0$ to 3.6 V,
 $V_{SS} = AVSS0 = AVSS1 = V_{REFL0} = V_{SS_USB} = V_{SS1_USBA} = V_{SS2_USBA} = PVSS_USBA = AVSS_USBA = 0$ V,
 $PCLKA = 8$ to 120 MHz, $PCLKB = 8$ to 60 MHz, $T_a = T_{opr}$
Output load conditions: $V_{OH} = V_{CC} \times 0.5$, $V_{OL} = V_{CC} \times 0.5$, $C = 30$ pF
High-drive output is selected by the driving ability control register.

Item			Symbol	Min.*1	Max.*1	Unit*1	Test Conditions*2	
RSPI	RSPCK clock cycle	Master	t_{SPcyc}	2	4096	t_{PAcyc}	Figure 5.46	
		Slave		8	4096			
	RSPCK clock high pulse width	Master	t_{SPCKWH}	$(t_{SPcyc} - t_{SPCKR} - t_{SPCKF}) / 2 - 3$	—	ns		
		Slave		$(t_{SPcyc} - t_{SPCKR} - t_{SPCKF}) / 2$	—			
	RSPCK clock low pulse width	Master	t_{SPCKWL}	$(t_{SPcyc} - t_{SPCKR} - t_{SPCKF}) / 2 - 3$	—	ns		
		Slave		$(t_{SPcyc} - t_{SPCKR} - t_{SPCKF}) / 2$	—			
	RSPCK clock rise/fall time	Output	t_{SPCKr}, t_{SPCKf}	—	5	ns		
		Input		—	1	μs		
	Data input setup time	Master	t_{SU}	6	—	ns	Figure 5.47 to Figure 5.52	
		Slave		$8.3 - t_{PAcyc}$	—			
	Data input hold time	Master	PCLKA division ratio set to 1/2	t_{HF}	0	—		ns
			PCLKA division ratio set to a value other than 1/2	t_H	t_{PAcyc}	—		
		Slave		$8.3 + 2 \times t_{PAcyc}$	—			
	SSL setup time	Master	t_{LEAD}	1	8	t_{SPcyc}		
		Slave		4	—	t_{PAcyc}		
	SSL hold time	Master	t_{LAG}	1	8	t_{SPcyc}		
		Slave		4	—	t_{PAcyc}		
	Data output delay time	Master	t_{OD}	—	6.3	ns		
		Slave		—	$3 \times t_{PAcyc} + 20$			
Data output hold time	Master	t_{OH}	0	—	ns			
	Slave		0	—				
Successive transmission delay time	Master	t_{TD}	$t_{SPcyc} + 2 \times t_{PAcyc}$	$8 \times t_{SPcyc} + 2 \times t_{PAcyc}$	ns			
	Slave		$4 \times t_{PAcyc}$	—				
MOSI and MISO rise/fall time	Output	t_{Dr}, t_{Df}	—	5	ns			
	Input		—	1	μs			
SSL rise/fall time	Output	t_{SSLr}, t_{SSLf}	—	5	ns			
	Input		—	1	μs			
Slave access time			t_{SA}	—	4	t_{PAcyc}	Figure 5.51, Figure 5.52	
Slave output release time			t_{REL}	—	3	t_{PAcyc}		

Note 1. t_{PAcyc} : PCLKA cycle

Note 2. We recommend using pins that have a letter ("A", "B", etc.) to indicate group membership appended to their names as groups. For the RSPI interface, the AC portion of the electrical characteristics is measured for each group.

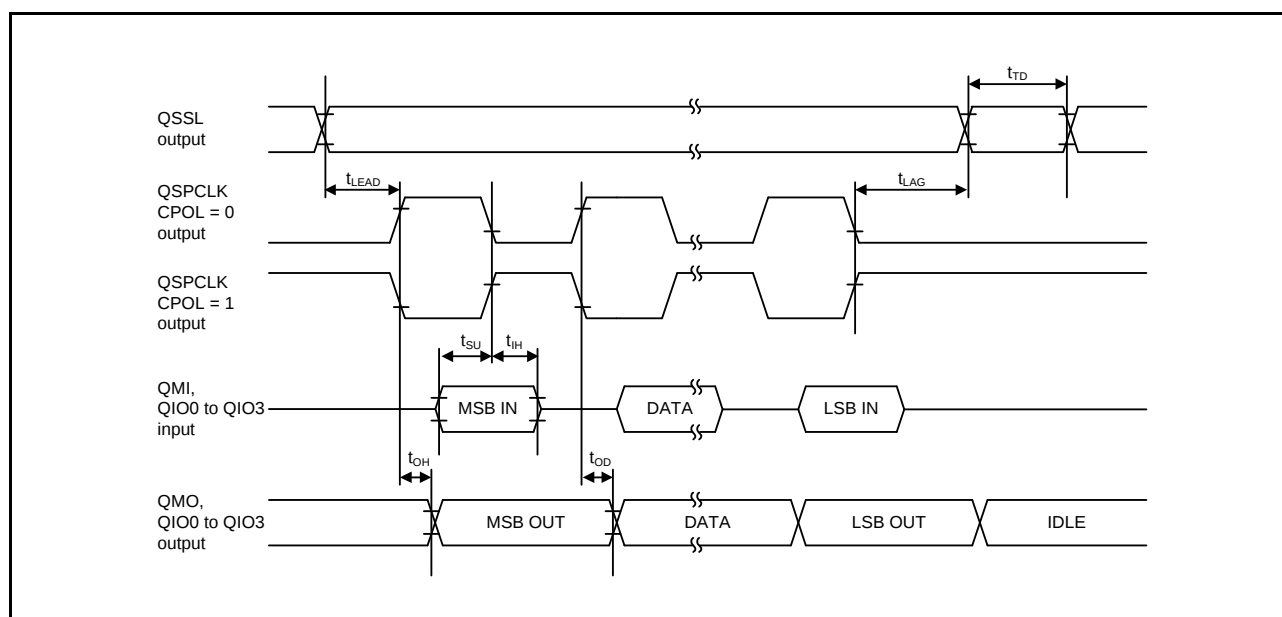
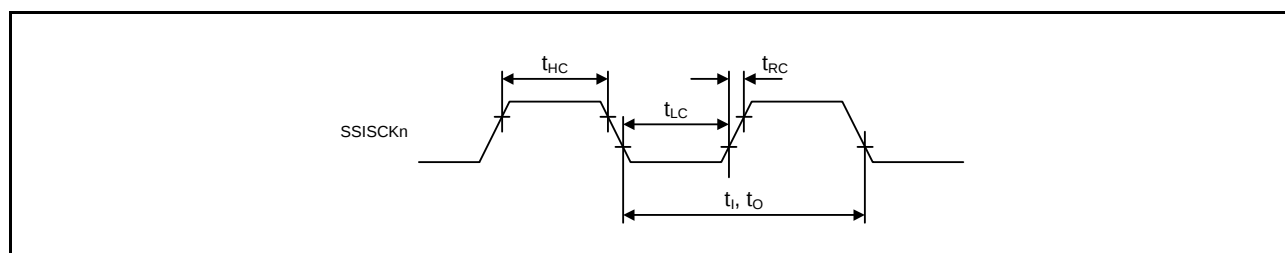
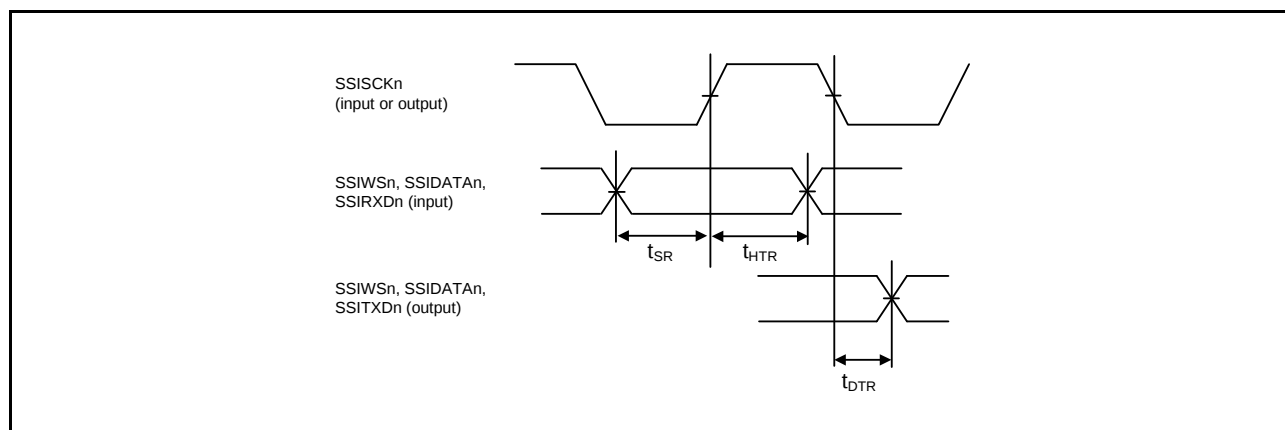


Figure 5.55 Transmit/Receive Timing (CPHA = 1)

Table 5.38 Serial Sound Interface Timing

Conditions: $V_{CC} = AVCC0 = AVCC1 = V_{CC_USB} = V_{BATT} = 2.7$ to 3.6 V, $2.7 \leq V_{REFH0} \leq AVCC0$,
 $V_{CC_USBA} = AVCC_USBA = 3.0$ to 3.6 V,
 $V_{SS} = AVSS0 = AVSS1 = V_{REFL0} = V_{SS_USB} = V_{SS1_USBA} = V_{SS2_USBA} = PVSS_USBA = AVSS_USBA = 0$ V,
 $PCLKA = 8$ to 120 MHz, $PCLKB = 8$ to 60 MHz, $T_a = T_{opr}$
 Output load conditions: $V_{OH} = V_{CC} \times 0.5$, $V_{OL} = V_{CC} \times 0.5$, $C = 30$ pF
 High-drive output is selected by the driving ability control register.

Item	Symbol	Min.	Max.	Unit	Test Conditions
SSI	AUDIO_CLK input frequency	t_{AUDIO}	—	50	MHz
	Output clock cycle	t_O	150	64000	ns
	Input clock cycle	t_I	150	64000	ns
	Clock high level	t_{HC}	60	—	ns
	Clock low level	t_{LC}	60	—	ns
	Clock rising time	t_{RC}	—	25	ns
	Data delay time	t_{DTR}	—5	25	ns
	Setup time	t_{SR}	25	—	ns
	Hold time	t_{HTR}	25	—	ns
	WS change edge SSIDATA output delay	t_{DTRW}	—	25	ns

**Figure 5.57 Clock Input/Output Timing****Figure 5.58 Transmit/Receive Timing (SSISCKn Rising Synchronous)**

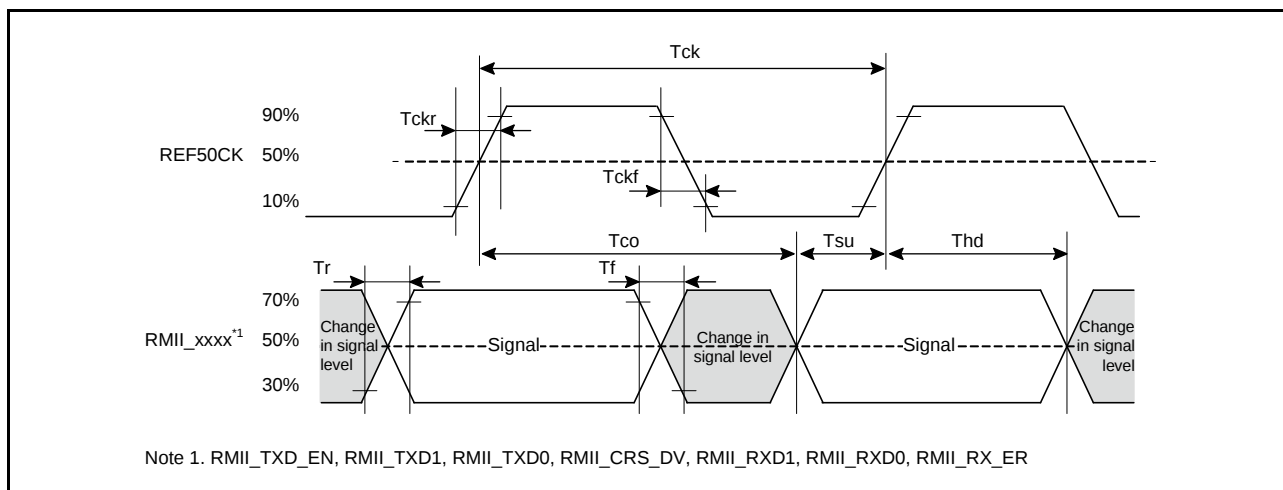


Figure 5.62 Timing with the REF50CK and RMII Signals

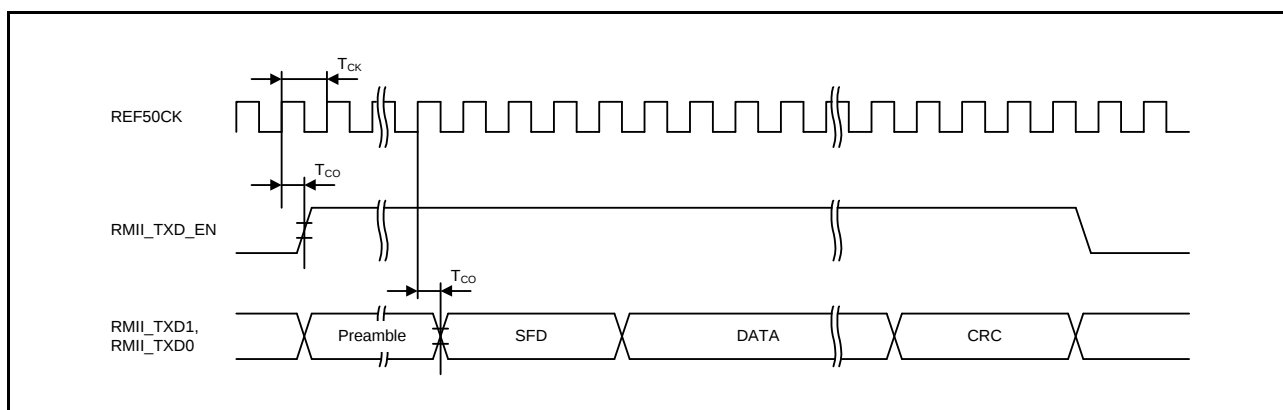


Figure 5.63 RMII Transmission Timing

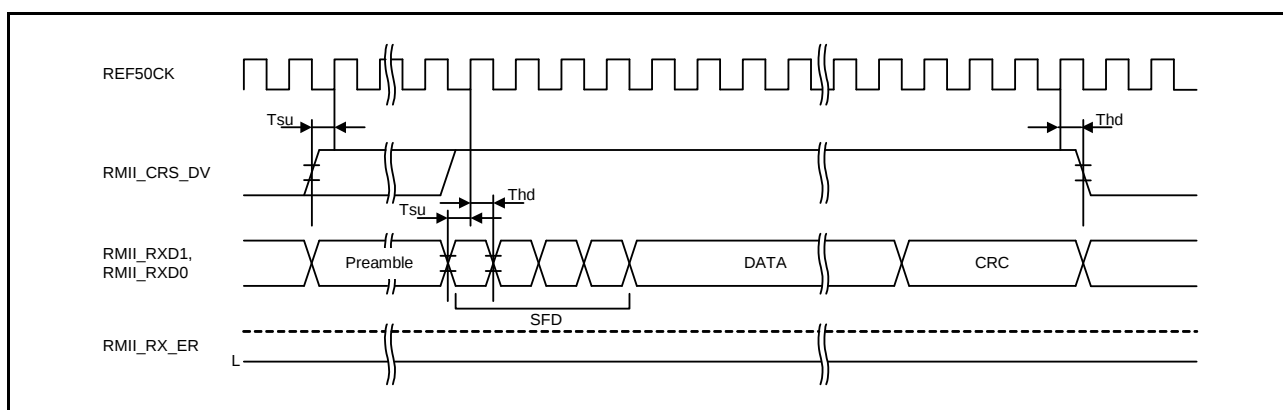


Figure 5.64 RMII Reception Timing (Normal Operation)

Table 5.46 12-Bit A/D (Unit 1) Conversion Characteristics

Conditions: $V_{CC} = AVCC0 = AVCC1 = V_{CC_USB} = V_{BATT} = 2.7$ to 3.6 V, $2.7 \leq V_{REFH0} \leq AVCC0$,
 $V_{CC_USBA} = AVCC_USBA = 3.0$ to 3.6 V,
 $V_{SS} = AVSS0 = AVSS1 = V_{REFL0} = V_{SS_USB} = V_{SS1_USBA} = V_{SS2_USBA} = PV_{SS_USBA} = AV_{SS_USBA} = 0$ V,
 $PCLKB = PCLKD = 1$ MHz to 60 MHz, $T_a = T_{opr}$

Item		Min.	Typ.	Max.	Unit	Test Conditions
Resolution		8	—	12	Bit	
Conversion time*1 (Operation at PCLK = 60 MHz)	Permissible signal source impedance (max.) = 1.0 kΩ	0.88 (0.667) *2	—	—	μs	Sampling in 40 states
Analog input capacitance		—	—	30	pF	
Offset error		—	±2.0	±3.5	LSB	
Full-scale error		—	±2.0	±3.5	LSB	
Quantization error		—	±0.5	—	LSB	
Absolute accuracy		—	±4.0	±6.0	LSB	
DNL differential nonlinearity error		—	±1.5	±2.5	LSB	
INL integral nonlinearity error		—	±2.0	±3.5	LSB	

Note: The above specification values apply when there is no access to the external bus during A/D conversion. If access proceeds during A/D conversion, values may not fall within the above ranges.

Note 1. The conversion time includes the sampling time and the comparison time. As the test conditions, the number of sampling states is indicated.

Note 2. The value in parentheses indicates the sampling time.

Table 5.47 A/D Internal Reference Voltage Characteristics

Conditions: $V_{CC} = AVCC0 = AVCC1 = V_{CC_USB} = V_{BATT} = 2.7$ to 3.6 V, $2.7 \leq V_{REFH0} \leq AVCC0$,
 $V_{CC_USBA} = AVCC_USBA = 3.0$ to 3.6 V,
 $V_{SS} = AVSS0 = AVSS1 = V_{REFL0} = V_{SS_USB} = V_{SS1_USBA} = V_{SS2_USBA} = PV_{SS_USBA} = AV_{SS_USBA} = 0$ V,
 $PCLKB = PCLKD = 60$ MHz, $T_a = T_{opr}$

Item	Min.	Typ.	Max.	Unit	Test Conditions
A/D internal reference voltage	1.20	1.25	1.30	V	

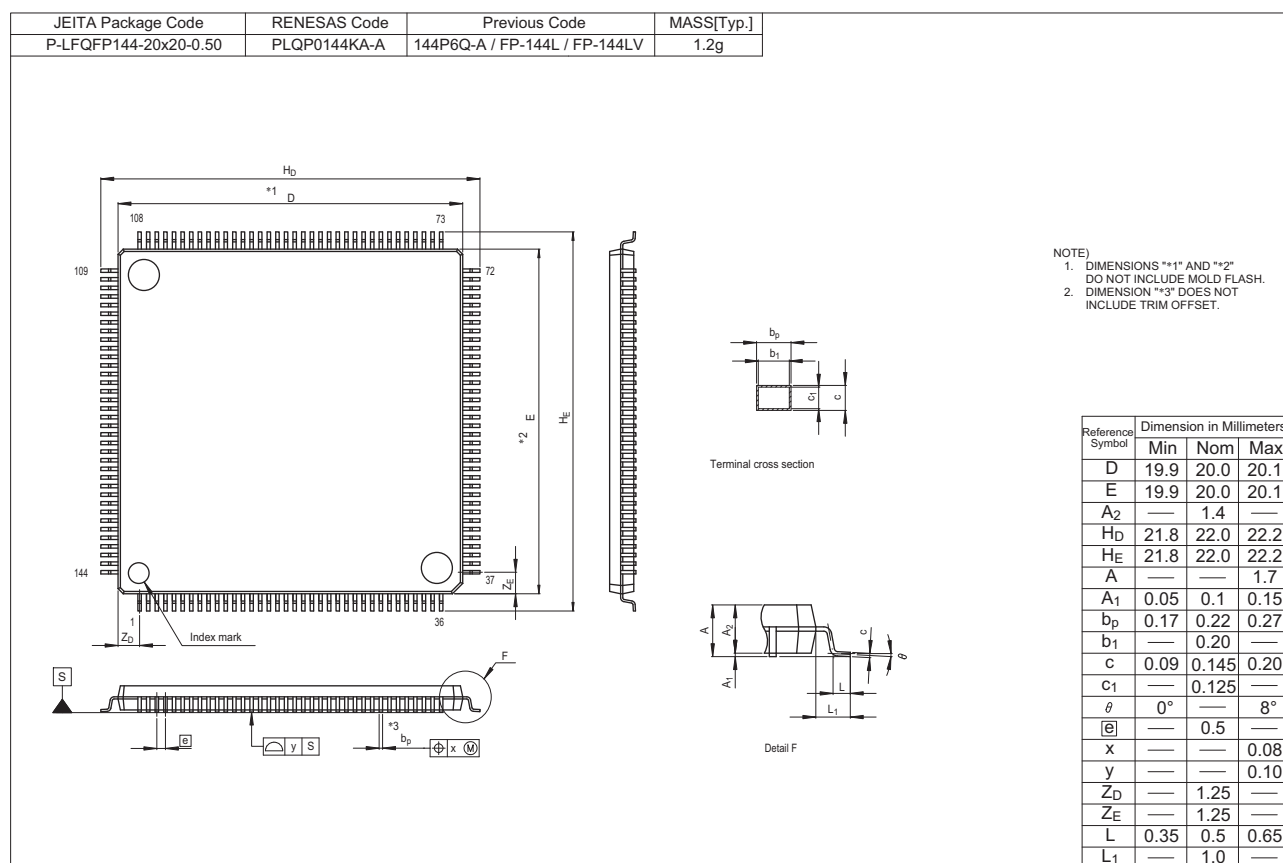


Figure E 144-Pin LFQFP (PLQP0144KA-A)

Rev.	Date	Description		Classification
		Page	Summary	
1.10	Oct 24, 2016	108	Table 4.1 List of I/O Registers (Address Order) (37 / 67) 0008 C296h, added	
		110	Table 4.1 List of I/O Registers (Address Order) (39 / 67), changed	TN-RX*-A152A/E
		111	Table 4.1 List of I/O Registers (Address Order) (40 / 67), changed	
		112	Table 4.1 List of I/O Registers (Address Order) (41 / 67), changed	
		119	Table 4.1 List of I/O Registers (Address Order) (48 / 67) 000C 0438h, 000C 046Ch, deleted	
		132, 133	Table 4.1 List of I/O Registers (Address Order) (61 / 67), (62 / 67), changed	
		138	Table 4.1 List of I/O Registers (Address Order), Note 6 added	TN-RX*-A152A/E
		5. Electrical Characteristics		
		139	Table 5.1 Absolute Maximum Rating, changed	TN-RX*-A160A/E
		140	Table 5.2 DC Characteristics (1), changed	TN-RX*-A159A/E TN-RX*-A160A/E
		141	Table 5.3 DC Characteristics (2), changed	TN-RX*-A159A/E
		183	Figure 5.48 RSPI Timing (Master, CPHA = 0) (Bit Rate: PCLKB Division Ratio Set to 1/2), changed	
		206	Table 5.49 Temperature Sensor Characteristics, changed	TN-RX*-A159A/E
		212	Figure 5.84 Battery Backup Function Characteristics, changed	
		213	Table 5.53 Code Flash Memory Characteristics, changed	TN-RX*-A146A/E
		214	Table 5.54 Data Flash Memory Characteristics, changed	

All trademarks and registered trademarks are the property of their respective owners.